

Title (en)
SILICONE-EPOXY RESIN COMPOSITION AND CONDUCTIVE ADHESIVE PREPARED THEREFROM

Publication
EP 0388473 A4 19920304 (EN)

Application
EP 89909855 A 19890901

Priority
• JP 22155588 A 19880902
• JP 30652288 A 19881202

Abstract (en)
[origin: WO9002768A1] A silicone-epoxy resin composition of this invention comprises a silicone-epoxy resin of general formula (I) and a curing agent. It has an excellent compatibility with an epoxy resin or curing agent and a high curing rate and, when cured, offers well-balanced flexibility, humidity resistance and heat resistance. Hence, it is effective for the bonding and sealing of electric or electronic components requiring a low stress. For example, a conductive adhesive prepared by adding a conductive filler to this composition can exhibit an excellent performance in the bonding of large-sized ICs or LSIs or in assembling quartz oscillators.

IPC 1-7
C08G 59/30; **C09J 3/16**

IPC 8 full level
C08G 59/30 (2006.01); **C09J 163/00** (2006.01); **H01B 1/22** (2006.01); **H01B 1/24** (2006.01)

CPC (source: EP)
C08G 59/306 (2013.01); **C09J 163/00** (2013.01); **H01B 1/22** (2013.01); **H01B 1/24** (2013.01); **C08L 2666/54** (2013.01)

Citation (search report)
• [X] BE 742710 A 19700605
• [X] DE 1251034 B
• [XP] EP 0319472 A2 19890607 - CIBA GEIGY AG [CH]
• [A] WORLD PATENTS INDEX LATEST Derwent Publications Ltd., London, GB; AN 85-015747 & JP-A-59 212 250 (MITSUBISHI ELECTRIC) 1 February 1984
• See references of WO 9002768A1

Cited by
US5227093A; EP0816461A3

Designated contracting state (EPC)
DE FR GB

DOCDB simple family (publication)
WO 9002768 A1 19900322; EP 0388473 A1 19900926; EP 0388473 A4 19920304

DOCDB simple family (application)
JP 8900905 W 19890901; EP 89909855 A 19890901